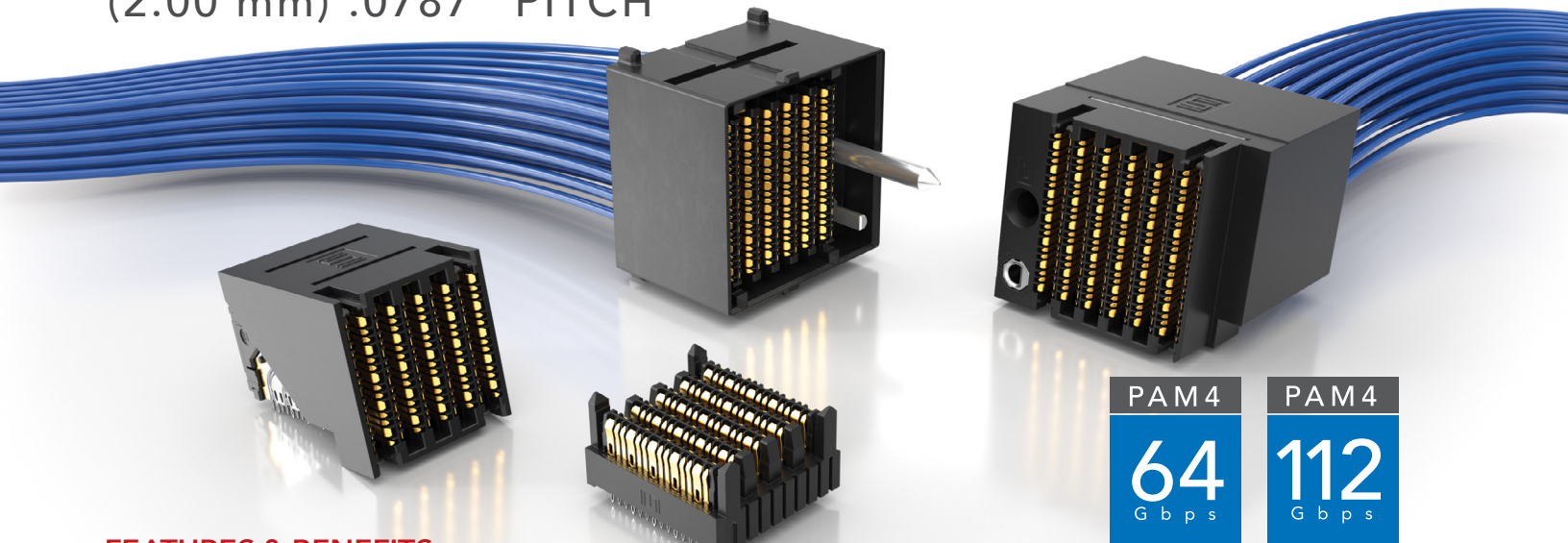


# ExaMAX<sup>®</sup>

## HIGH-SPEED BACKPLANE CONNECTOR & CABLE SYSTEMS

(2.00 mm) .0787" PITCH



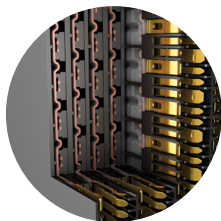
### FEATURES & BENEFITS

#### ExaMAX<sup>®</sup> High-Speed Backplane System

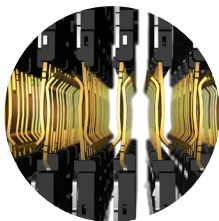
- Meets a variety of industry specifications
- Traditional, coplanar and direct mate orthogonal
- 24 - 72 pair designs (4 and 6 pairs; 6, 8, 10 and 12 columns)
- Shielded wafer design reduces crosstalk and includes one sideband signal per column
- Press-fit tails provide a reliable electrical connection
- PCIe<sup>®</sup> 6.0/CXL<sup>®</sup> 3.2 capable

#### ExaMAX<sup>®</sup> High-Speed Backplane Cable Assemblies

- 30 & 34 AWG Eye Speed<sup>®</sup> ultra low skew twinax cable
- 34 AWG Eye Speed Thinax<sup>™</sup> ultra low skew twinax cable
- Offers improved signal integrity, increased flexibility and routability
- Highly customizable with modular flexibility
- Reduce costs due to lower layer counts
- PCIe<sup>®</sup> 6.0/CXL<sup>®</sup> 3.2 capable



Staggered  
Differential  
Pair Design



Two Reliable Points  
of Contact with  
a 2.4 mm Wipe



In Development:  
Open-Pin-Field,  
Coplanar Configuration



In Development:  
2 Pair Design for  
a Lower Profile



In Development:  
ExaMAX2<sup>®</sup> 8 Pairs  
for 112 Gbps PAM4  
Performance

### KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
EBTM/EBTF/EBDM	Liquid Crystal Polymer	Copper Alloy	Sn or Au over 50 $\mu$ " (1.27 $\mu$ m) Ni	-55 °C to +105 °C	4 A per pin	150 VAC/212 VDC	Yes
EPTT/EPTS	High Temperature Thermoplastic	Copper Alloy	Sn or Au over 50 $\mu$ " (1.27 $\mu$ m) Ni	-55 °C to +105 °C	14.1 A per pin	150 VAC/212 VDC	Yes
EBCM/EBCF	Liquid Crystal Polymer	Copper Alloy	Au over 50 $\mu$ " (1.27 $\mu$ m) Ni	-40 °C to +105 °C	2.6 A per pin	125 VAC/177 VDC	N/A

PCI-SIG<sup>®</sup>, PCI Express<sup>®</sup> and the PCIe<sup>®</sup> design marks are registered trademarks and/or service marks of PCI-SIG.

## ExaMAX<sup>®</sup> POWER MODULES

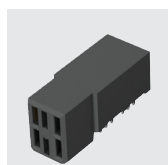
### (2.00 mm) .0787" PITCH TERMINAL POWER MODULES



**EPTT**  
Mates with:  
**EPTS**

EPTT	POSITIONS PER ROW	PLATING	HEIGHT	D	ORIENTATION
	-2 = 4 Positions	-P = Palladium with flash Gold on contacts, Matte Tin on tails	-11.5 = (11.50 mm) .453"		-RA = Right-Angle

### (2.00 mm) .0787" PITCH SOCKET POWER MODULES



**EPTS**  
Mates with:  
**EPTT**

EPTS	POSITIONS PER ROW	PLATING	D	ORIENTATION	PIN STAGING
	-2 = 4 Positions	-P = Palladium with flash Gold on contacts, Matte Tin on tails		-VT = Vertical  -RA = Right-Angle	Visit website for dimensions.  -01 thru -06 (Vertical)  -04 & -08 (Right-Angle)

View complete specifications at: [samtec.com?EPTT](http://samtec.com?EPTT) & [samtec.com?EPTS](http://samtec.com?EPTS)

## ExaMAX<sup>®</sup> GUIDE MODULES

### TERMINAL GUIDE MODULES



**EGBM**  
Mates with:  
**EGBF**  
Insulator Material:  
**Zinc Alloy**

EGBM	ORIENTATION	THREADING	LENGTH	CARD SPACING
	-VT = Vertical  -RA = Right-Angle	Leave Blank for -RA  -1 = External  -2 = Internal (25.3 Length only)	Leave Blank for -RA  -18.3 = 18.30 mm (.720")  -25.3 = 25.30 mm (.996")	-20 = 20 mm (.787")

### SOCKET GUIDE MODULES



**EGBF**  
Mates with:  
**EGBM**  
Insulator Material:  
**Zinc Alloy**

EGBF	ORIENTATION	CARD SPACING
	-RA = Right-Angle	-20 = 20 mm (.787")

#### Notes:

Some lengths, styles and options are non-standard, non-returnable.

ExaMAX<sup>®</sup> is a registered trademark of AFCL.

View complete specifications at: [samtec.com?EGBM](http://samtec.com?EGBM) & [samtec.com?EGBF](http://samtec.com?EGBF)